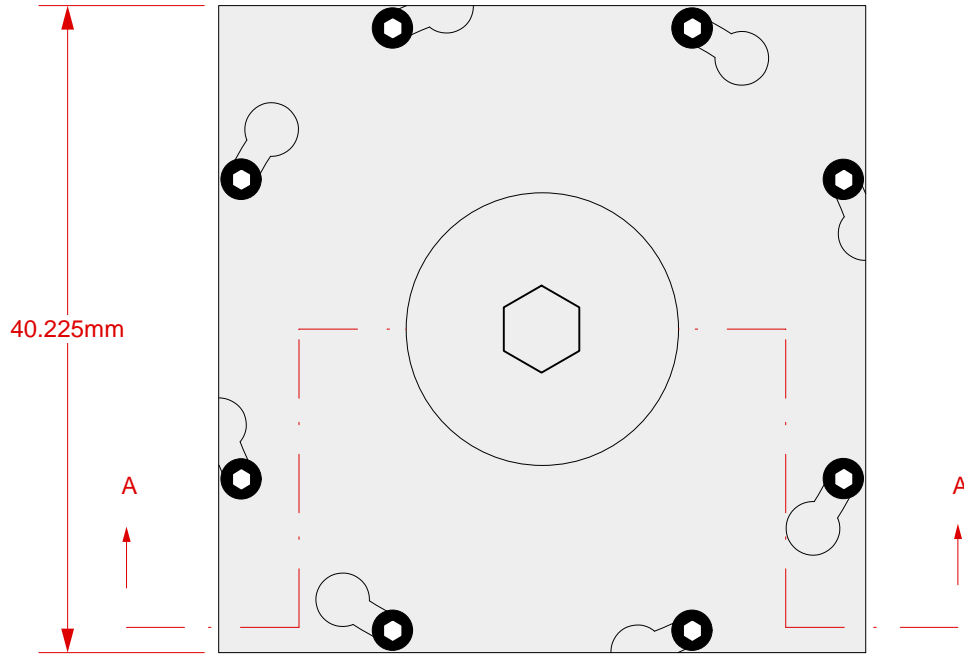


GHz BGA Socket - Direct mount, solderless

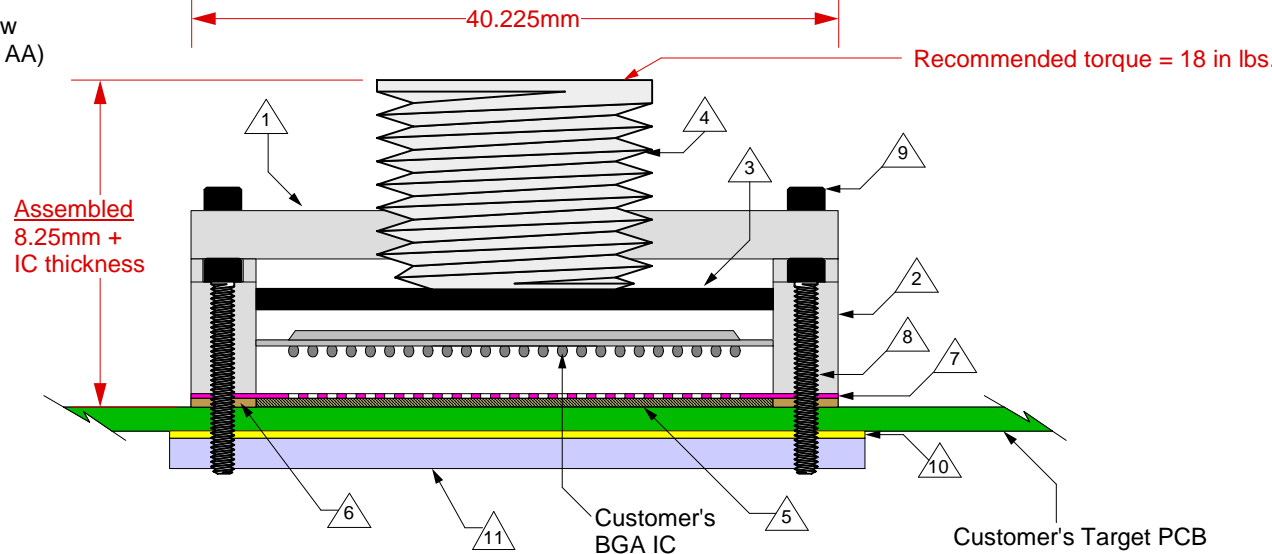
Top View



Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

Side View
(Section AA)



- | | |
|----|--|
| 1 | Socket Lid: Black anodized Aluminum.
Thickness = 2.5mm. |
| 2 | Socket base: Black anodized Aluminum.
Thickness = 6.5mm. |
| 3 | Compression Plate: Black anodized Aluminum.
Thickness = 2.5mm. |
| 4 | Compression screw: Clear anodized Aluminum.
Thickness = 5mm, Hex socket = 5mm. |
| 5 | Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle).
Thickness = 0.75mm. |
| 6 | Elastomer Guide: Cirlex or equivalent.
Thickness = 0.75mm. |
| 7 | Ball Guide: Kapton polyimide. |
| 8 | Socket base screw: Socket head cap, 18-8 Stainless steel, 0-80 fine thread , 19.05mm long. |
| 9 | Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread. |
| 10 | Insulation Plate: FR4/G10, Thickness = 1.59mm. |
| 11 | Backing Plate: Black anodized Aluminum.
Thickness = 6.35mm. |

SG-BGA-6069 Drawing

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PO BOX 21151 ST. PAUL, MN 55121
Tele: (651) 452-8100
www.ironwoodelectronics.com

Status: Released

Scale: -

Rev: C

Drawing: H. Hansen

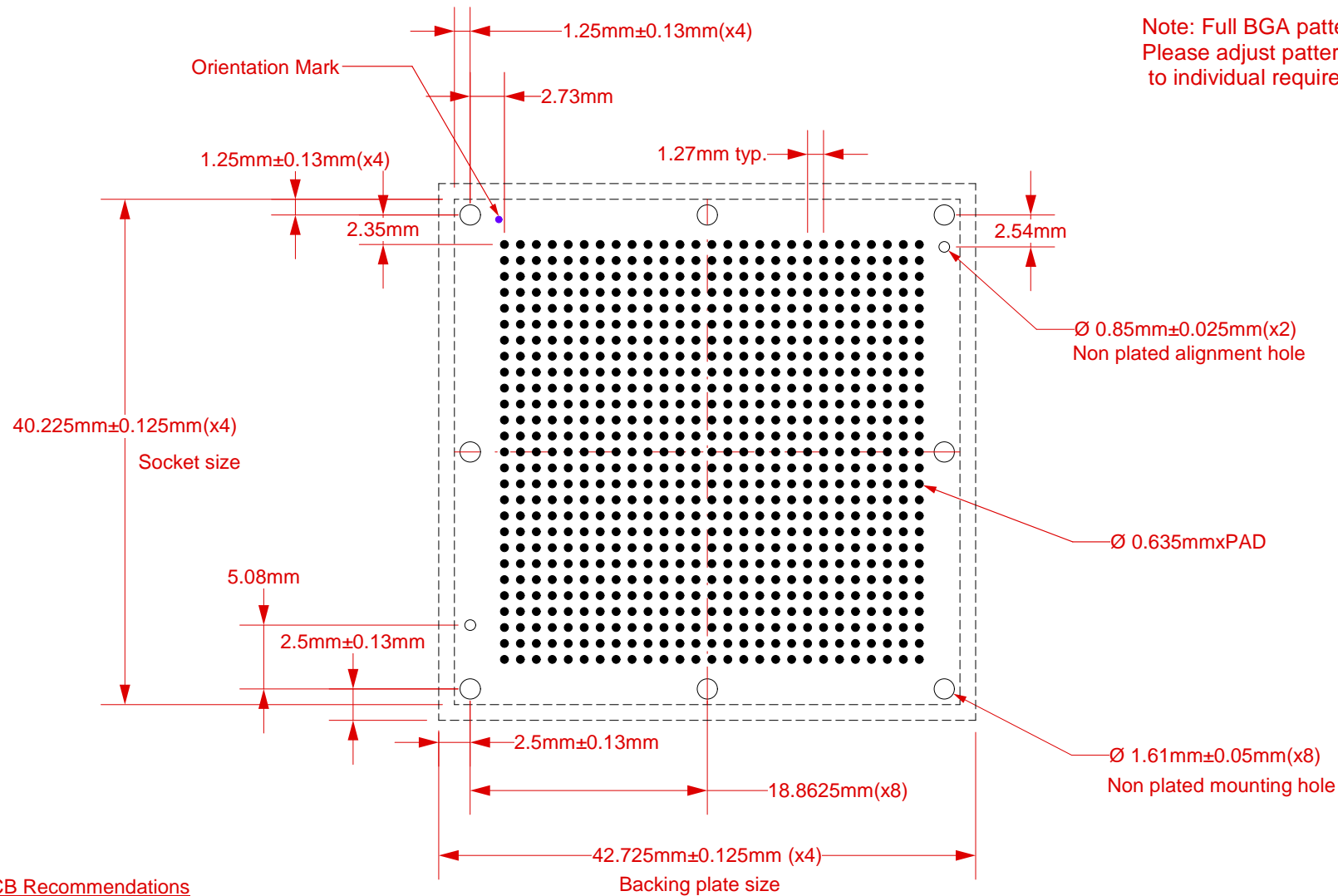
Date: 12/27/02

File: SG-BGA-6069 Dwg.mcd

Modified: 5/19/08

All tolerances: ± 0.125 mm (unless stated otherwise). Materials and specifications are subject to change without notice.

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**




Note: Full BGA pattern shown.
Please adjust pattern according to individual requirements.

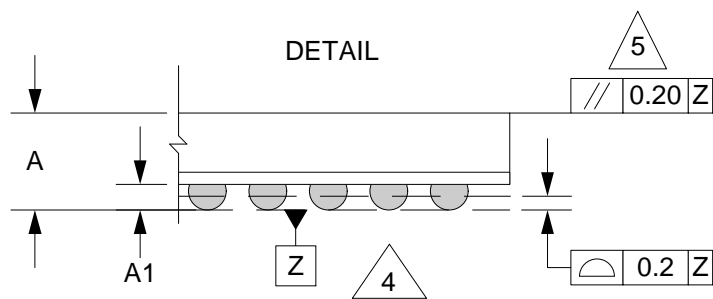
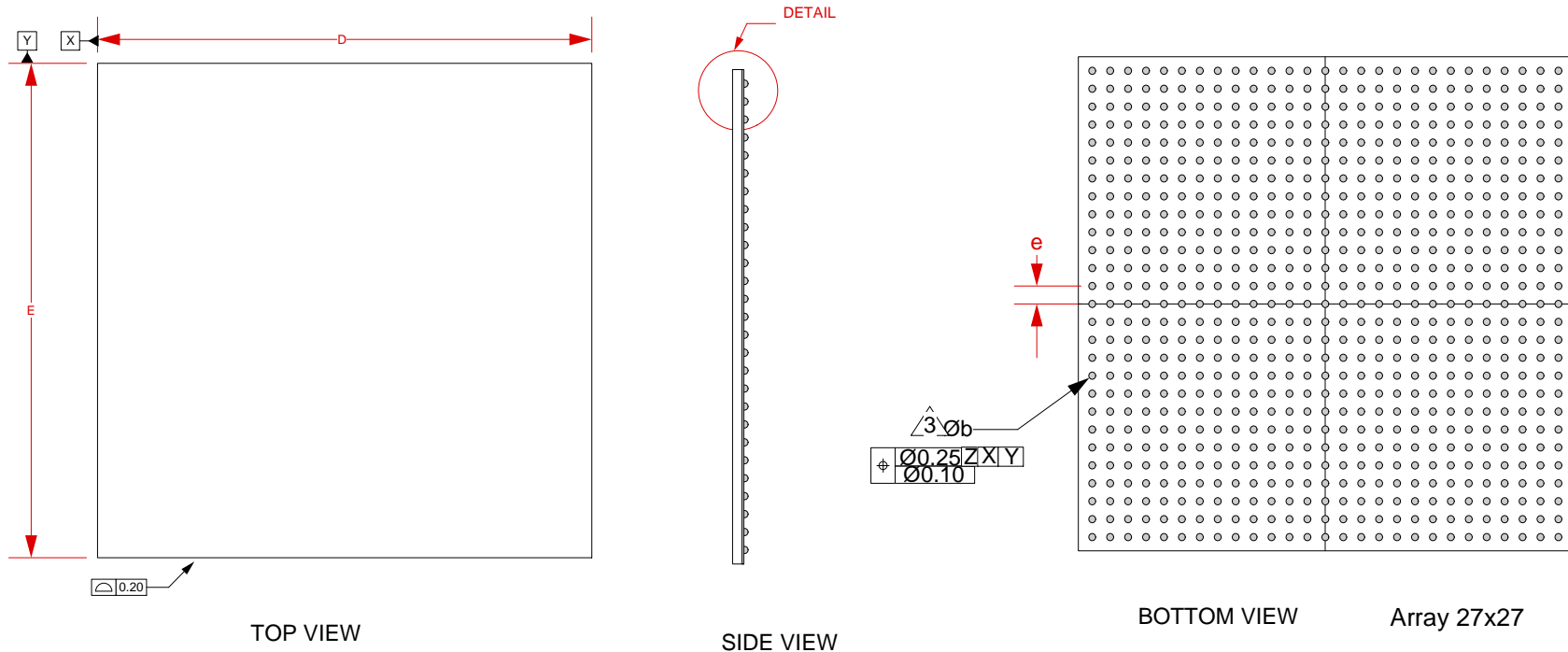
Target PCB Recommendations

- Total thickness: 2.4mm minimum
- Plating: Gold or Solder finish
- PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

	SG-BGA-6069 Drawing	Status: Released	Scale: 2:1	Rev: C
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1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- △3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
 - △4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
 - △5 Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		3.5
A1	0.35	0.55
b		0.90
D	35.0 BSC	
E	35.0 BSC	
e	1.27 BSC	

SG-BGA-6069 Drawing

Status: Released

Scale: -

Rev: C

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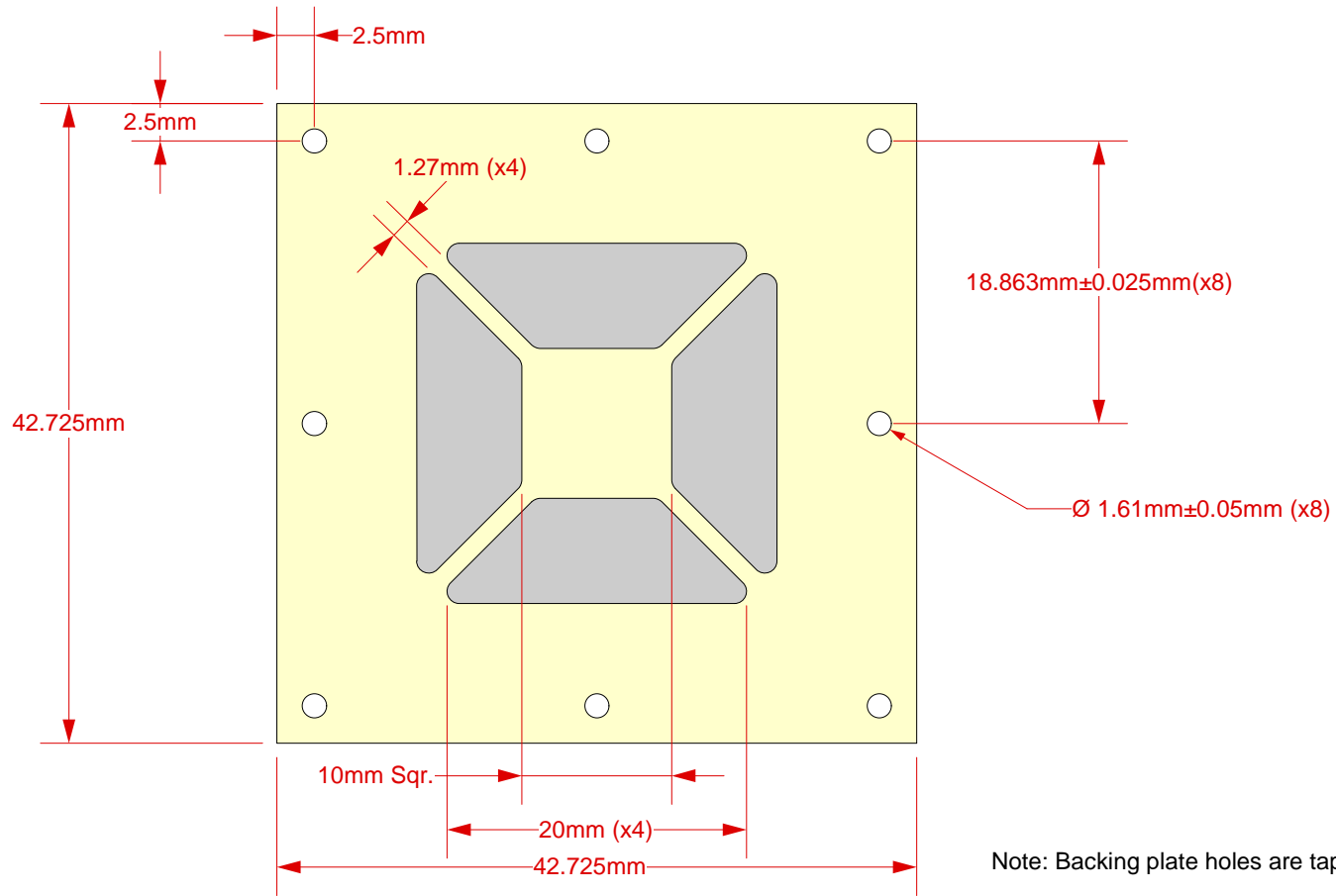
Drawing: H. Hansen

Date: 12/27/02

File: SG-BGA-6069 Dwg.mcd

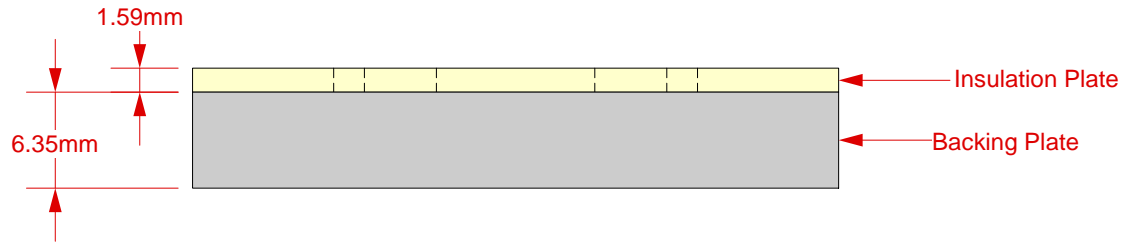
Modified: 5/19/09

Top View




Note: Backing plate holes are tapped to accept 0-80 screws.

Side View



Description: Insulation Plate and Backing Plate

	SG-BGA-6069 Drawing	Status: Released	Scale: -	Rev: C
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